





PROGRAM

REGISTRATION

2022 International Conference on Electronics Packaging May 11-14, 2022 Sapporo Community Plaza, Hokkaido, Japan

## IEEE EPS Japan Chapter Young Award of ICEP 2022

SPONSOR

VENUE

Presented to Dr. Jowesh Goundar (Tohoku University)

For the paper

"Strain-Induced Change in the Photonic Properties of Dumbbell-Shaped Graphene Nanoribbon Structures"